



KL 95

ceramic filled adhesive film

Applications

Thermal connection of

- ◆ MOSFETS
 - ◆ CPUs, LEDs
 - ◆ Flips Chips, DSPs
 - ◆ BGAs, PPGAs
- on heat sinks

Representatives

- ◆ Power supplies and inverter modules
- ◆ Computers
- ◆ Telecommunication electronics
- ◆ Automotive electronic

Properties	Unit	KL 95
Colour		grey
		Filled Acrylic Polymer
Thermal Properties		
Thermal conductivity λ^*	W/mK	1.3
Thermal resistance R_{th}^*	K/W	0.32
Electrical Properties		
Breakdown voltage $U_{d; ac}$	kV	2
Dielectric breakdown $E_{d; ac}$	kV/mm	10
Volume resistivity	Ωm	2.0×10^{11}
Dielectric loss factor $\tan \delta$	(1KHz)	2.4×10^{-1}
Dielectric constant ϵ_r	(1KHz)	1.7
Mechanical Properties		
Measured thickness (+/-10%)	mm	0.180
Hardness	Shore A	60
Tensile shear strength ⁺	N/cm ²	>6.5
Tensile shear strength ⁺ (Temperature aging)	1h/65°C	26.90
	24h/65°C	34.30
	72h/65°C	48.80
Physical Properties		
Adhesion** (bonding strength)	Nmm	>0.5
Tack** (surface Adhesiveness)	mm	>1.0
Density	g/cm ³	2.24
Application temperature	°C	-40 to +100
Possible thickness	mm	0.18 - 0.3

The Keratherm© - KL 95 is a highly filled multifunctional adhesive tape. Characteristic are the good thermal conductivity, good dielectric properties and excellent adhesive behavior. The adhesive tape is very suitable for bonding a wide variety of electronic components and heat sinks.

+ Tensile sheare strength Alu/Foil/Alu – 25x25 mm²(outsourcing – 48h/RT);

* Measured thickness 0,18 mm; ** used measurement – Texture Analyser (TA.XT-plus)

Data for engineer guidance only.
Observed performance varies in application.
Engineers are reminded to test the material in application.